

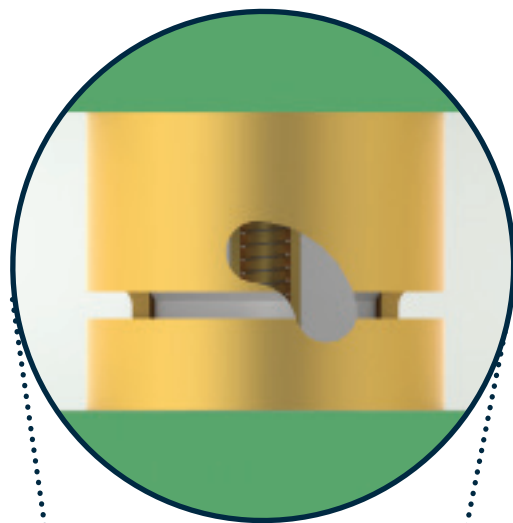
3mm Board-to-Board Interconnect

Features & Benefits

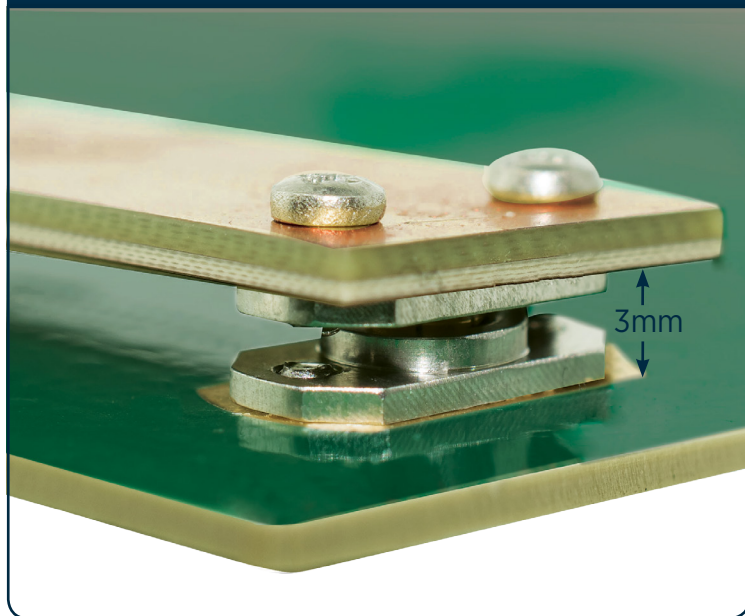
- 3mm board-to-board spacing
- .150" minimum pitch between adjacent connectors
- DC - 40 GHz
- Low-force, solderless installation does not damage PCB
- Easy to assemble, solderless design reduces yield and assembly time
- Lowest stacked height (3 mm) of any board-to-board high frequency coaxial connection system

Applications

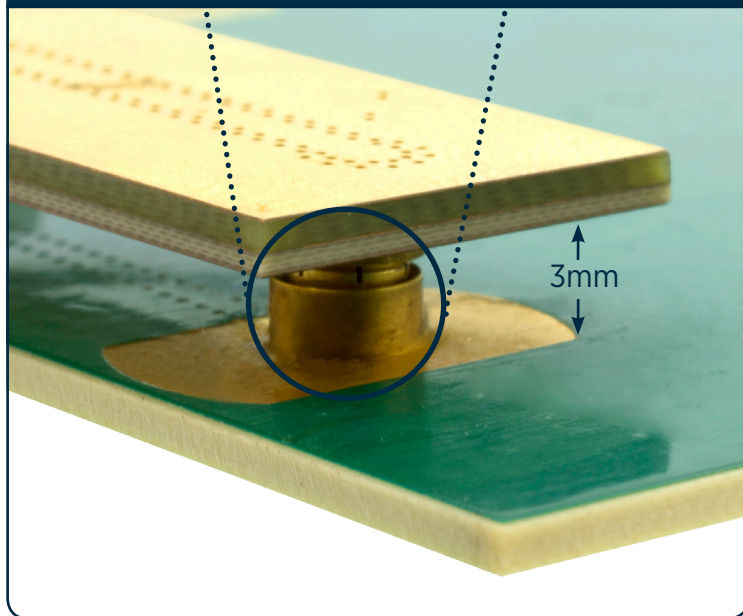
- Embedded computing
- High density stacked PCB applications
- High density multiport applications



Solderless



Solder-On



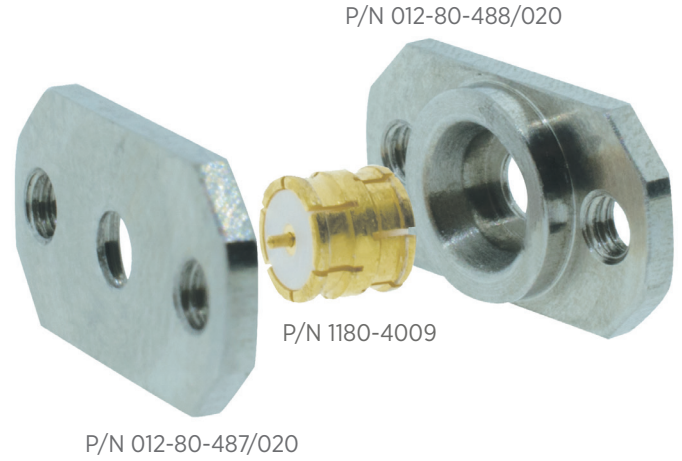
Specifications

Electrical

Frequency Range	DC - 40 GHz		
Impedance	50Ω		
VSWR	Stripline	DC to 18 GHz	1.10 : 1
		DC to 40 GHz	1.30 : 1
Insertion Loss	Stripline	DC to 18 GHz	.30 dB
		DC to 40 GHz	.60 dB

Mechanical

Board-to-Board Spacing	.1134" Min, .1184" Max
Engage Force into SB / Disengage Force from SB	2.8 lbs typ / 2.5 lbs typ
Engage Force into FD / Disengage Force from FD	3.4 lbs typ / 3.0 lbs typ
Axial Misalignment	.005"
Radial Misalignment	.007"
Mating Cycles (min)	500
Temperature Range	-65 to +165°C



Unmated



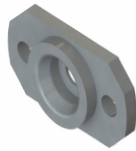
Mated



Part Numbers

3mm Male Shroud (Thread-In)

P/N: 012-80-487/020



3mm Male Shroud (Solder-On)

P/N: 012-80-485/185



3mm Male Shroud (Thread-In, Detent)

P/N: 012-80-488/020



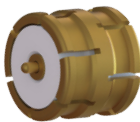
3mm Male Shroud (Solder-On, Detent)

P/N: 012-80-484/185



3mm Female to Female Bullet

P/N: 1180-4009



3mm Extraction Tool

P/N: 500-80-014

